

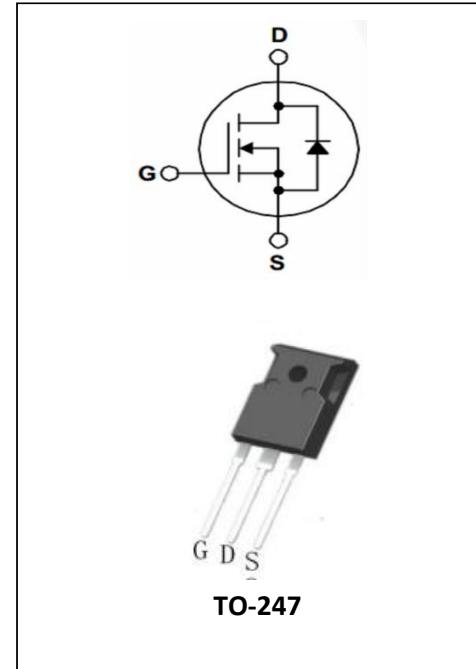
Silicon N-Channel Power MOSFET

Description

The MD50N50 uses advanced technology and design to provide excellent RDS(ON) . It can be used in a wide variety of applications.

General Features

- ① $V_{DS}=500V, I_D=50A$
- ② Low ON Resistance
- ③ Low Reverse transfer capacitances
- ④ 100% Single Pulse avalanche energy Test



Application

- ① Power switching application
- ② Adapter and charger

Electrical Characteristics @ $T_a=25^\circ C$ (unless otherwise specified)

Absolute Maximum Ratings:

Symbol	Parameter	Value	Units
V_{DSS}	Drain-to-Source Breakdown Voltage	500	V
I_D	Drain Current (continuous) at $T_c=25^\circ C$	50	A
I_{DM}	Drain Current (pulsed)	160	A
V_{GS}	Gate to Source Voltage	+/-30	V
P_{tot}	Total Dissipation at $T_c=25^\circ C$	250	W
T_j	Max. Operating Junction Temperature	175	$^\circ C$
E_{AS}	Single Pulse Avalanche Energy	3200	mJ

Electrical Parameters:

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{DS}	Drain-source Voltage	$V_{GS}=0V, I_D=250\mu A$	500			V
$R_{DS(on)}$	Static Drain-to-Source on-Resistance	$V_{GS}=10V, I_D=15A$		0.09	0.12	Ω
$V_{GS(th)}$	Gated Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.5	3.5	4.5	V



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I _{DSS}	Drain to Source leakage Current	V _{DS} =500V, V _{GS} = 0V			1.0	μA
I _{GSS(F)}	Gated to Source Foward Leakage	V _{GS} = +30V			100	nA
I _{GSS(R)}	Gated to Source Reverse Leakage	V _{GS} = -30V			-100	nA
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, f=1.0MHZ		7857.9		pF
C _{oss}	Output Capacitance			751.2		pF
C _{rss}	Reverse Transfer Capacitance			29.7		pF

Switching Characteristics

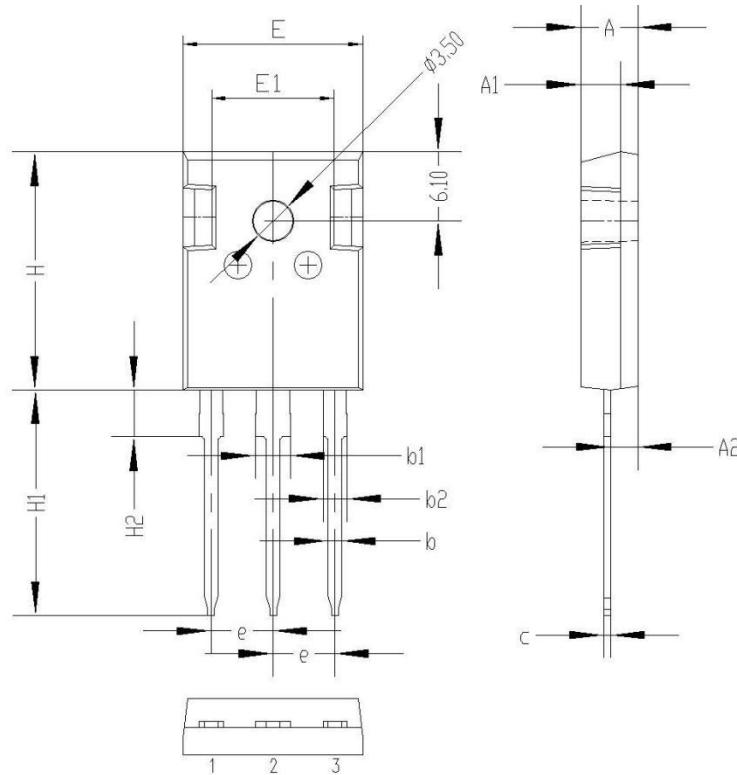
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t _{d(on)}	Turn-on Delay Time	V _{DD} =250V,I _D =30A, R _G =25 Ω		68		nS
t _r	Turn-on Rise Time			141		nS
t _{d(off)}	Turn-off Delay Time			213		nS
t _f	Turn-off Fall Time			97.3		nS
Q _g	Total Gate Charge	V _{DS} =400V I _D =30A V _{GS} =10V		153		nC
Q _{gs}	Gate-Source Charge			36.3		nC
Q _{gd}	Gate-Drain Charge			57.9		nC

Source-Drain Diode Characteristics

Symbol	Paramet	Test Conditions	Min	Typ	Max	Unit
I _{SD}	S-D Current(Body Diode)				40	A
I _{SDM}	Pulsed S-D Current(Body Diode)				160	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{DS} =20A			1.5	V
t _{rr}	Reverse Recovery Time	T _J =25 °C, I _F =88A di/dt=100A/us			482	nS
Q _{rr}	Reverse Recovery Charge				8.5	μC
	*Pulse Test: Pulse Width <= 300μs, Duty Cycle< =2%					

Symbol	Parameter	Typ	Units
R _{θJC}	Junction-to-Case	0.6	°C/W

Package Description



Symbol	Unit mm		
	Min	Typ	Max
A	4.8	5.00	5.20
A1	3.3	3.5	3.7
A2	2.20	2.40	2.60
b	1.00	1.2	1.40
b1	2.90	3.10	3.30
b2	1.80	2.00	2.20
c	0.50	0.60	0.70
e	5.25	5.45	5.65
E	15.2	15.7	16.2
H	20.8	21	21.2
H1	19.5	20.0	20.5
H2	3.9	4.1	4.3
G	5.9	6.1	6.3
ΦP	3.30	3.50	3.70

TO-247 Package

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NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shenzhen Minos reserves the right to make changes in this specification sheet and is subject to change without prior notice.

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